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Mark Your Calendar for EPTC 2007

CALL FOR PAPERS

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About EPTC

The 9th Electronics Packaging Technology Conference (EPTC 2007) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter, sponsored by IEEE CPMT Society with technical sponsorship from IMAPS.

EPTC 2007 will feature technical sessions, short courses and exhibition. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world.

Conference Topics

You are invited to submit an abstract presenting new development in the following categories:

- Advanced Packaging: *Wafer level packaging, 3D integration, embedded passives & actives on substrates, high power modules, SiP and other system integration technologies and ultra thin embedded modules, RF-ID, disposable electronics packaging and high pin count flip chip packaging.*
- Emerging Technologies: *Packaging solutions for MEMS, Bio-electronics, Automotive electronics, optoelectronics, organic and printable electronics. MEMS packaging for inertial MEMS, microrelays bio-MEMS, RF and optical MEMS.* Optoelectronics packaging of *components and modules, development of Gbps and Tbps opto-electronics, photonic interconnects and backplanes, design and development of optical passive components, photonic crystal based devices, development of process and assembly methods for Silicon Photonic components.*
- Interconnection Technologies: *Gold and copper wire bonding and flip chip (eutectic/lead-free solders) on standard and copper low-k wafers, solder replacement flip chip (ICP, ACP, ACF, NCP), under bump metallurgy, 3D and through Si via connections, microvia and build-up technologies, fine pitch interconnects, nano interconnects.*
- Manufacturing Technologies: *Sustainable volume production of advanced packages and emerging technologies. New manufacturing technologies focusing on incorporating rapid product changes, cost, yield improvement, electrical/mechanical and environmental performance.*
- Materials & Processes: *Advancements in adhesives, encapsulants, underfills, solder alloys, ROHS compliant materials, flexible dielectrics, ceramics, composites, thin film processes on laminates, nano-materials and assembly processes, advanced material characterization techniques.*
- Electrical Modeling & Signal Integrity: *Modeling simulation & measurement for coupling, signal Integrity, power integrity & decoupling scheme analysis reflection, switching noise, EMI/EMC analysis on package & subsystems, RF modules, time & frequency domain measurements for advanced modules.*
- Thermal Characterization & Cooling Solutions: *Modeling & simulation methodology for thermal characterization of advanced packaging, modules & systems. Novel thermal management solutions. Enhanced air & liquid cooling techniques, Hot-spot management.*
- Mechanical Modeling & Structural Integrity: *Thermo-mechanical modeling at package, board & system levels. Modeling of delamination, moisture diffusion, hygrostress, thermal cycling, drop impact, bend, vibration, solder joint reliability and life prediction, measurement of material & interface properties, experimental verification.*
- Quality & Reliability: *Component, board and system level reliability assessment, interfacial adhesion, accelerated testing and models, advances in reliability test methods and failure analysis.*
- Poster Session: *Papers from all categories above are considered.*

Important Dates

15th May 2007	**Submission of abstract**
15th June 2007	**Notification of Acceptance**
15th August 2007	**Submission of manuscript**

Abstract and Paper Submission

Abstracts are solicited to describe original and unpublished work. The abstract should be about 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories for abstract review. All submissions must be in English and should be made via the online submission system found at http://www.eptc-ieee.net. The required file format is **Adobe Acrobat® PDF** or **MS Word** in one single file for each submission.

The abstracts must be received by 15th May 2007. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Special gifts will be given to the first 10 submitted abstracts which are subsequently accepted and published. Authors will be notified of paper acceptance and publication instruction by 15th June 2007. The final manuscript for publication in the conference proceedings is due by 15th August 2007.

Outstanding Technical Papers

The conference proceedings is an official IEEE publication. Author(s) of Outstanding Technical Paper(s) and Best Student Paper will receive an award at the next conference.

Call for Short Courses

The conference program includes half and full-day short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in subsequent mailings. Proposals for short courses can be submitted to Dr. Albert Lu (cwlu@simtech.a-star.edu.sg).

Call for Exhibition

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference. Potential exhibitors may contact Dr. Yoon (yoonsw@ime.a-star.edu.sg) for details.

Conference information & contacts: **Website: http://www.eptc-ieee.net** **Email: secretariat@eptc-ieee.net**

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